

Soldered RSAM data sheet RSAM-λ-12.7s

GaAs chip area standard: 4mm x 4mm

optional: other dimensions on request

Chip thickness standard: 400 µm

Front side the RSAM is covered by a dielectric front mirror.

The rSAM chip is soldered on a gold plated Cu-cylinder with 12.7 mm Ø using a Pb/Sn solder. The solder provides a low thermal resistance between the rSAM and the mount.

The standard position of the rSAM is at the center of the mount.

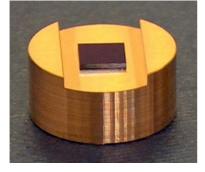
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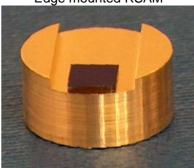
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• Optional the rSAM can be mounted on the edge of the mount without extra charges.

Center mounted RSAM



Edge mounted RSAM



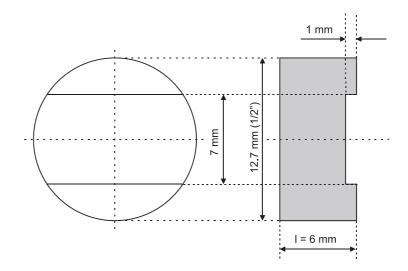
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Local Court Jena HRB 112769

Mount

Cu-cylinder, $\varnothing = 12.7 \text{ mm}$ I = 6.0 mm



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